PROCEEDINGS OF SPIE

Photomask Japan 2018: XXV Symposium on Photomask and Next-Generation Lithography Mask Technology

Kiwamu Takehisa
Editor

18–20 April 2018
Yokohama, Japan

Organized by
Photomask Japan
SPIE

Co-organized by
BACUS
EMLC

In Cooperation with
The Japan Society of Applied Physics
The Japan Society for Precision Engineering
The Institute of Electrical Engineering (Japan)
Technical Exhibit in Cooperation with SEMI (Japan)

Supported by
City of Yokohama

Published by
SPIE

Volume 10807

Proceedings of SPIE 0277-786X, V. 10807

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Photomask Japan 2018: XXV Symposium on Photomask and Next-Generation Lithography
Mask Technology, edited by Kiwamu Takehisa, Proc. of SPIE Vol. 10807, 1080701
© 2018 SPIE · CCC code: 0277-786X/18/$18 · doi: 10.1117/12.2504156

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Author(s), "Title of Paper," in *Photomask Japan 2018: XXV Symposium on Photomask and Next-Generation Lithography Mask Technology*, edited by Kiwamu Takehisa, Proceedings of SPIE Vol. 10807 (SPIE, Bellingham, WA, 2018) Seven-digit Article CID Number.

ISSN: 0277-786X
ISSN: 1996-756X (electronic)

ISBN: 9781510622012
ISBN: 9781510622029 (electronic)

Published by
SPIE
P.O. Box 10, Bellingham, Washington 98227-0010 USA
Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445
SPIE.org
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